

ABSTRACT OF THE DISCLOSURE

In a method of manufacturing an electroconductive film, a developing process is implemented on a photosensitive paste layer (12) having a height of about 13 μm in a state where exposure is repeated twice in Fig. 1D, and thereafter, a baking process is completed to form a wiring pattern (20). As a result, the curling of an edge formed in the wiring pattern (20) can be remarkably reduced.